## 3.0x2.0mm SURFACE MOUNT LED LAMP

Part Number: AA3021ES

High Efficiency Red

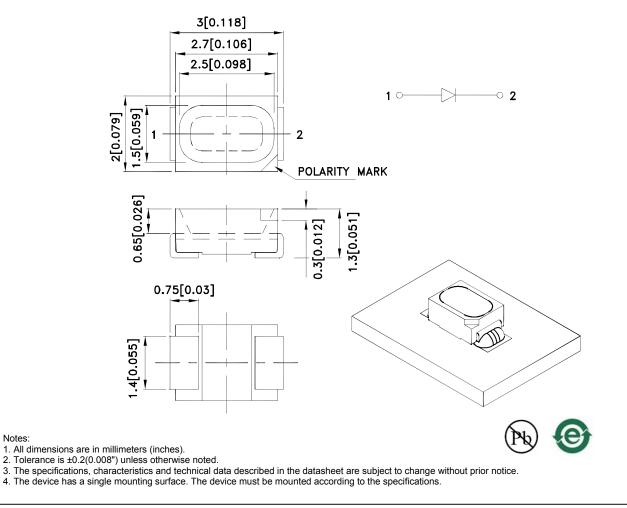
#### Features

- 3.0mm x 2.0mm, 1.3mm high, only minimum space required.
- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

#### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

#### Package Dimensions

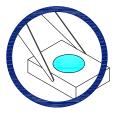


SPEC NO: DSAL0967 APPROVED: WYNEC REV NO: V.2 CHECKED: Allen Liu DATE: MAR/18/2011 DRAWN: J.Yu PAGE: 1 OF 6 ERP: 1201006921

### **Handling Precautions**

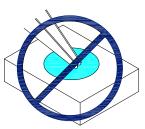
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.





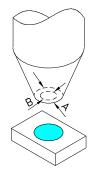
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.

4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.

4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

DATE: MAR/18/2011 DRAWN: J.Yu

#### Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA Min. Typ.		Viewing Angle [1]
					201/2
AA3021ES	High Efficiency Red (GaAsP/GaP)	Water Clear	10	30	125°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	I⊧=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	I⊧=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	IF=20mA
lr	Reverse Current	High Efficiency Red		10	uA	Vr=5V

Notes:

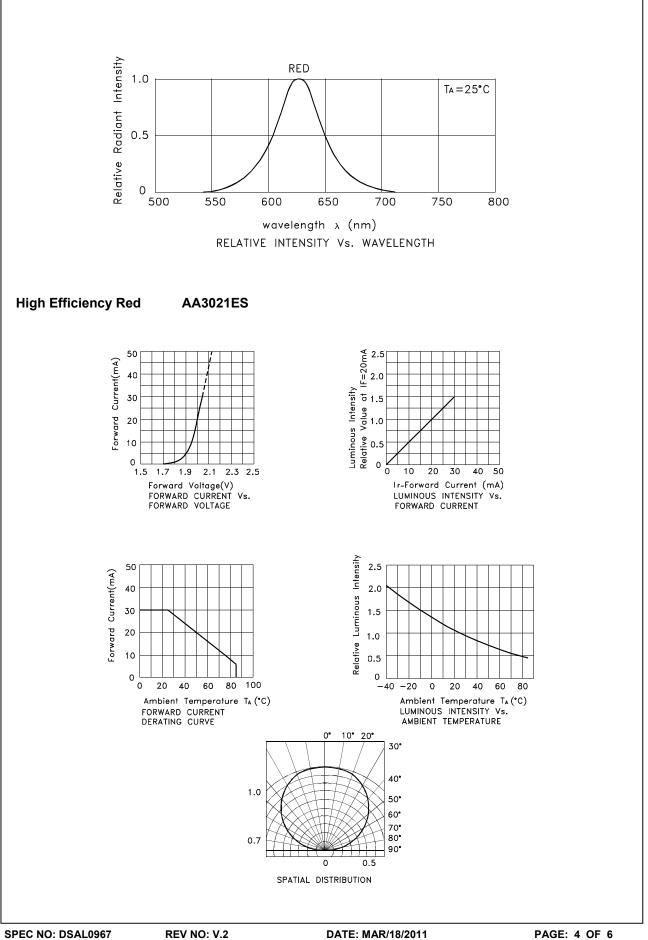
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

#### Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

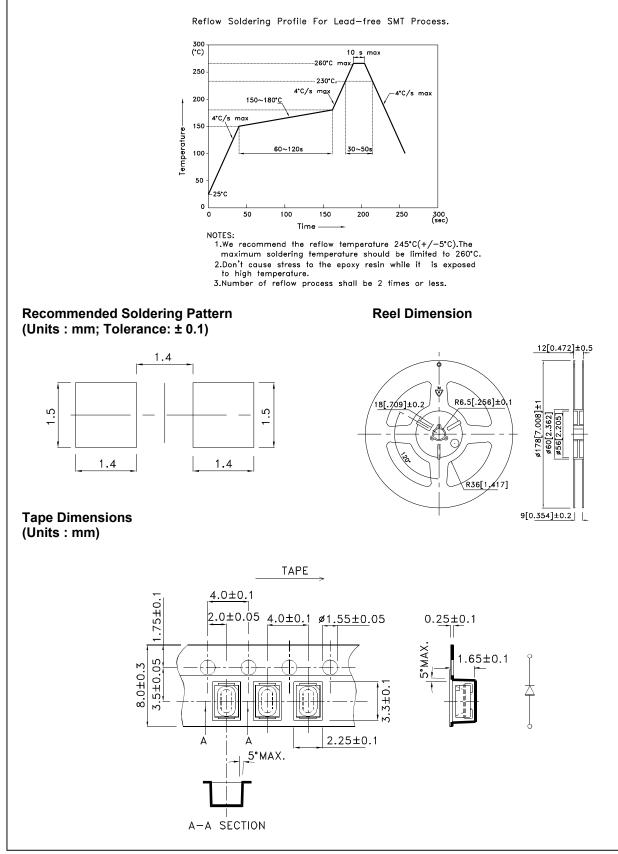
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



## AA3021ES

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.



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